



LEAD FREE ALLOYS

Alloy	Melting Point °C	Comment
Sn100C	227	Stabilised Tin/Copper giving bright joints and superior drainage to standard tin copper.
Sn99.3/Cu0.7	227	Cost-effective alternative for wave soldering and hand soldering applications. Suffers from poor drainage.
Sn97/Cu3	227-300	Cost effective alloy for high-temperature applications only.
Sn97/Sb3	232-238	Alloy with similar properties to Sn95/Sb/5
Sn95/Sb5	232-240	Alloy for high temperature applications only. Poor wetting. Less cost prohibitive than Sn/Ag.
Sn99 0.3Ag/0.7Cu	217-228	Low cost alternative to high silver alloys but with extended plastic range.
Sn/Ag3.0/Cu0.5	217-218	Silver-Copper Alloy with higher cost of metals.
Sn/Ag3.8-4/Cu 0.7	217	High silver-tin-silver-copper eutectic alloy.
Sn96.5/Ag3.5	221	This alloy has a known history within the electronics industry as it has been extensively used in the past for it higher temperature characteristics.
Sn95/Ag5	221-240	Alloy for high-temperature applications only.
Sn42/Bi57/Ag1	138	Similar characteristics to Sn42/Bi58 with improved fatigue characteristics.
In52/Sn48	118	Alloy for low temperature applications. Costly due to high indium content.
Sn42/Bi58	138	Alloy for low temperature applications. Potential embrittlement fatigue properties.
In97/Ag3	143	Alloy for low temperature applications. Costly due to high indium and silver content
Sn91/Zn9	199	Suffers from very high corrosion and oxidation of Sn/Zn alloys Requires special flux formulation. Short shelf-life.

Please contact us for further information on availability in various forms i.e. chunks, stick, bar, ingots and paste.

This data is based on information believed to be reliable and is offered in good faith but DKL Metals Ltd. makes no warranties either expressed or implied as to its accuracy and assumes no liabilities.

Page 1 of 1